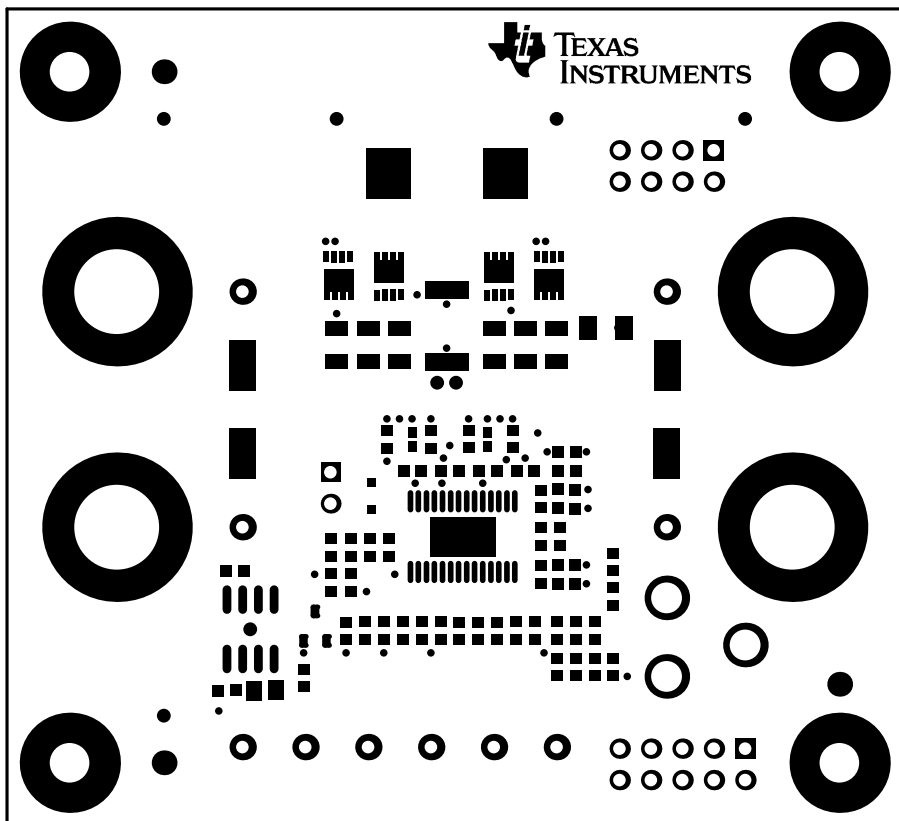
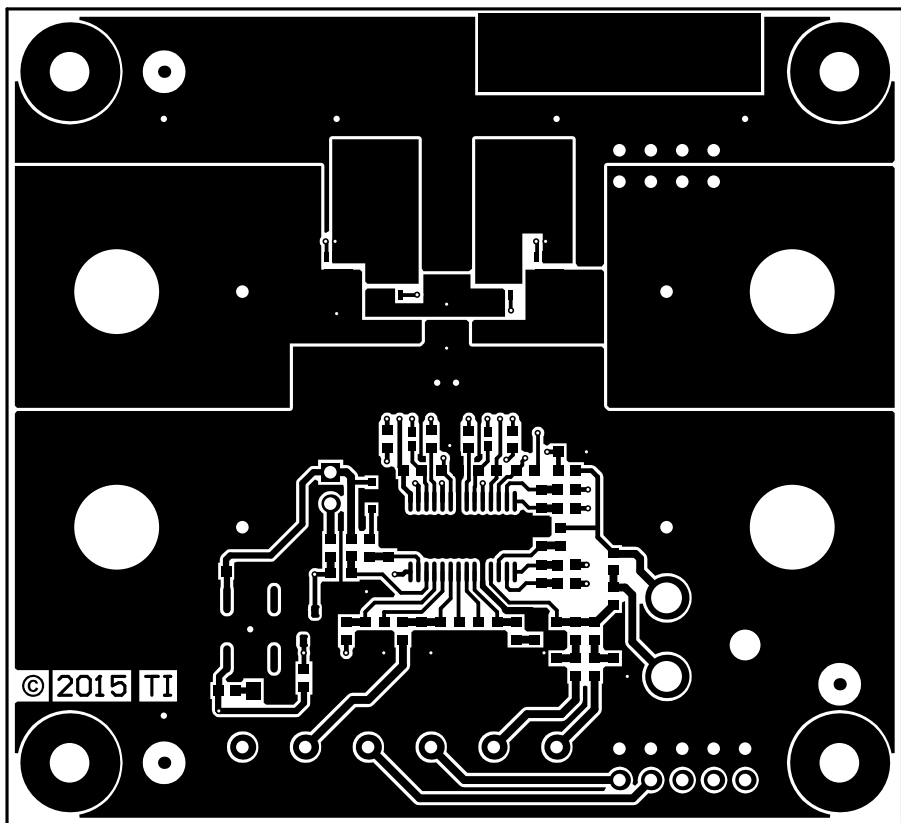


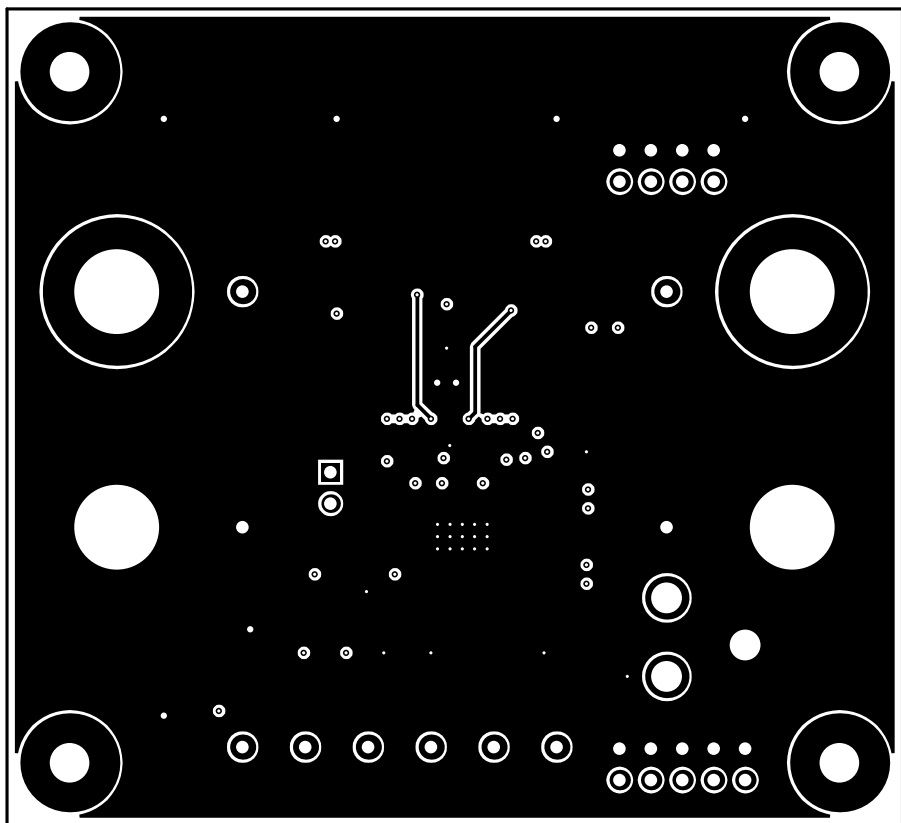
|                                  |                      |             |                                |
|----------------------------------|----------------------|-------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP10624    | REV: A      | SUN REV: Not In VersionControl |
| LAYER NAME = Top Overlay         |                      |             |                                |
| PLOT NAME = Top Overlay          | GENERATED : 4/7/2015 | 11:31:38 AM | TEXAS INSTRUMENTS              |



|                                  |                      |             |                                |
|----------------------------------|----------------------|-------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP10624    | REV: A      | SUN REV: Not In VersionControl |
| LAYER NAME = Top Solder          |                      |             |                                |
| PLOT NAME = Top Solder Mask      | GENERATED : 4/7/2015 | 11:31:39 AM | TEXAS INSTRUMENTS              |



|                                  |                                  |                   |                                |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP10624                | REV: A            | SUN REV: Not In VersionControl |
| LAYER NAME = Top Layer           |                                  |                   |                                |
| PLOT NAME = Top Layer            | GENERATED : 4/7/2015 11:31:40 AM | TEXAS INSTRUMENTS |                                |



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: PMP10624

REV: A

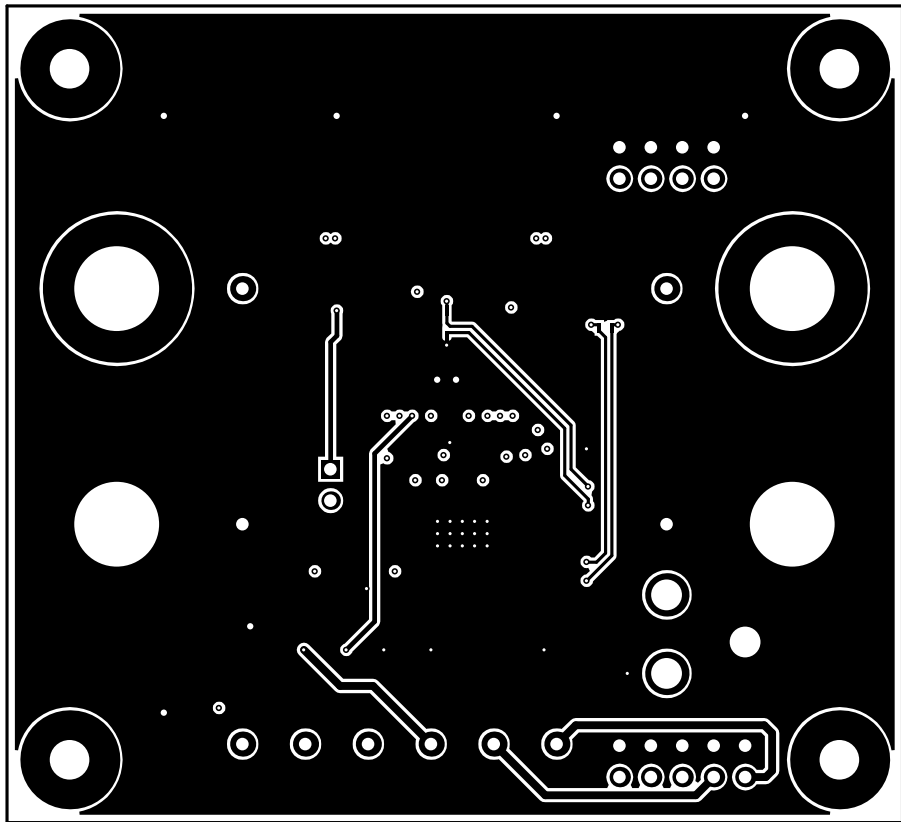
SUN REV: Not In VersionControl

LAYER NAME =

PLOT NAME = MidLayer1

GENERATED : 4/7/2015 11:31:41 AM

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: PMP10624

REV: A

SUN REV: Not In VersionControl

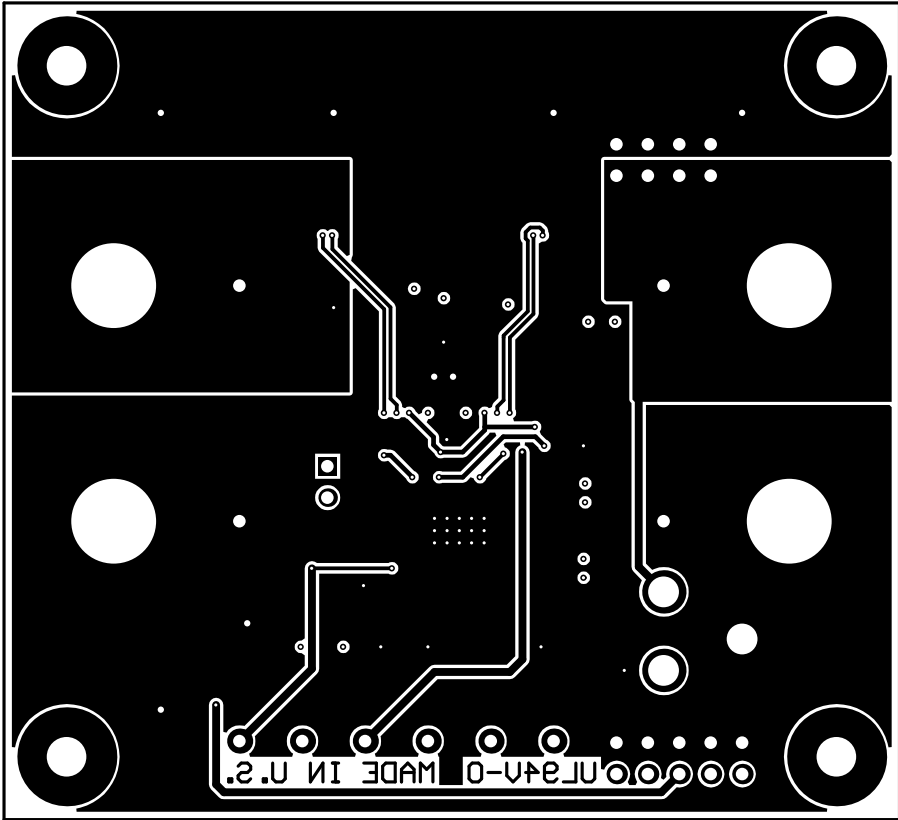
LAYER NAME =

PLOT NAME = MidLayer2

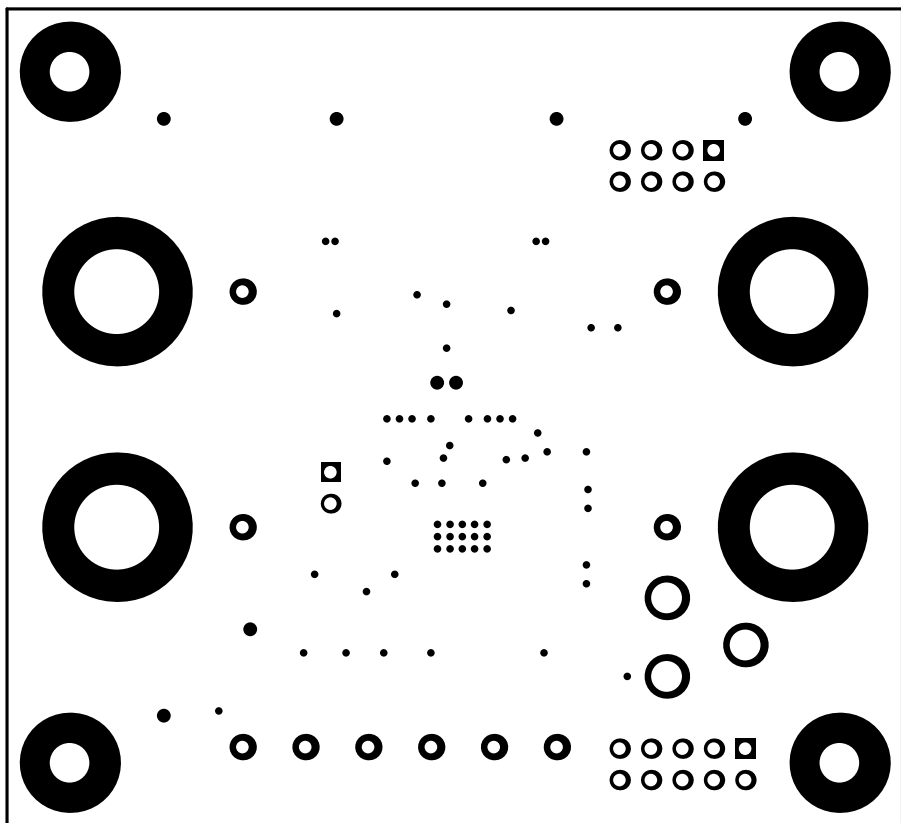
GENERATED : 4/7/2015 11:31:41 AM

TEXAS INSTRUMENTS

SUN: Not In VersionControl



|                                  |                                  |                   |                                |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP10624                | REV: A            | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Layer        |                                  |                   |                                |
| PLOT NAME = Bottom Layer         | GENERATED : 4/7/2015 11:31:42 AM | TEXAS INSTRUMENTS |                                |



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: PMP10624

REV: A

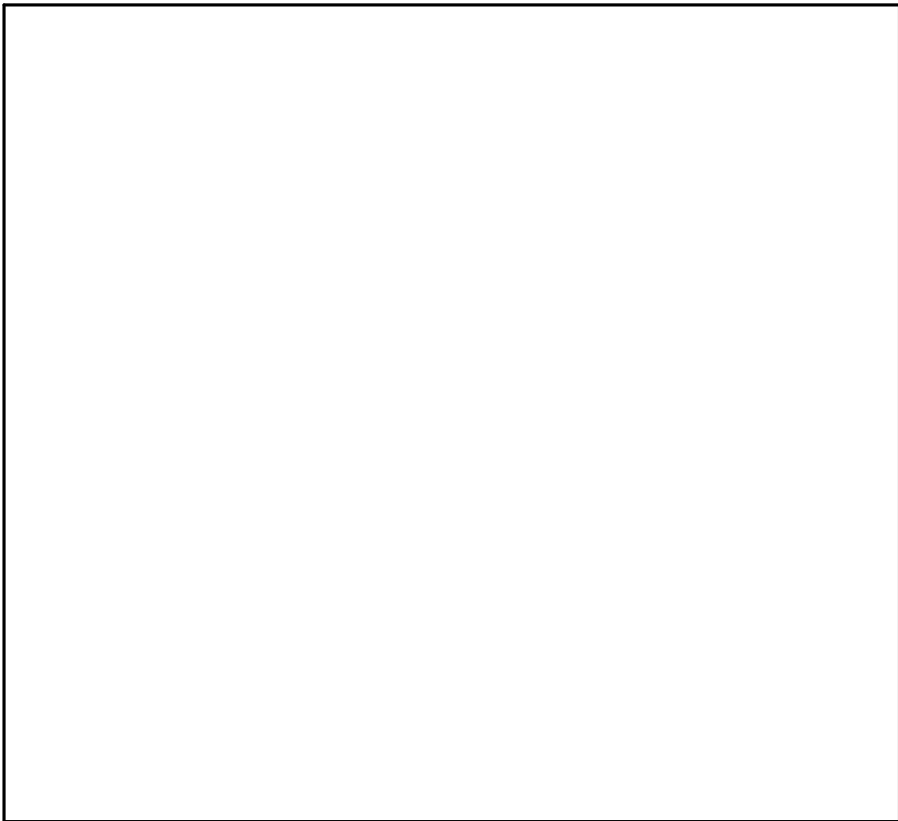
SUN REV: Not In VersionControl

LAYER NAME = Bottom Solder

PLOT NAME = Bottom Solder Mask

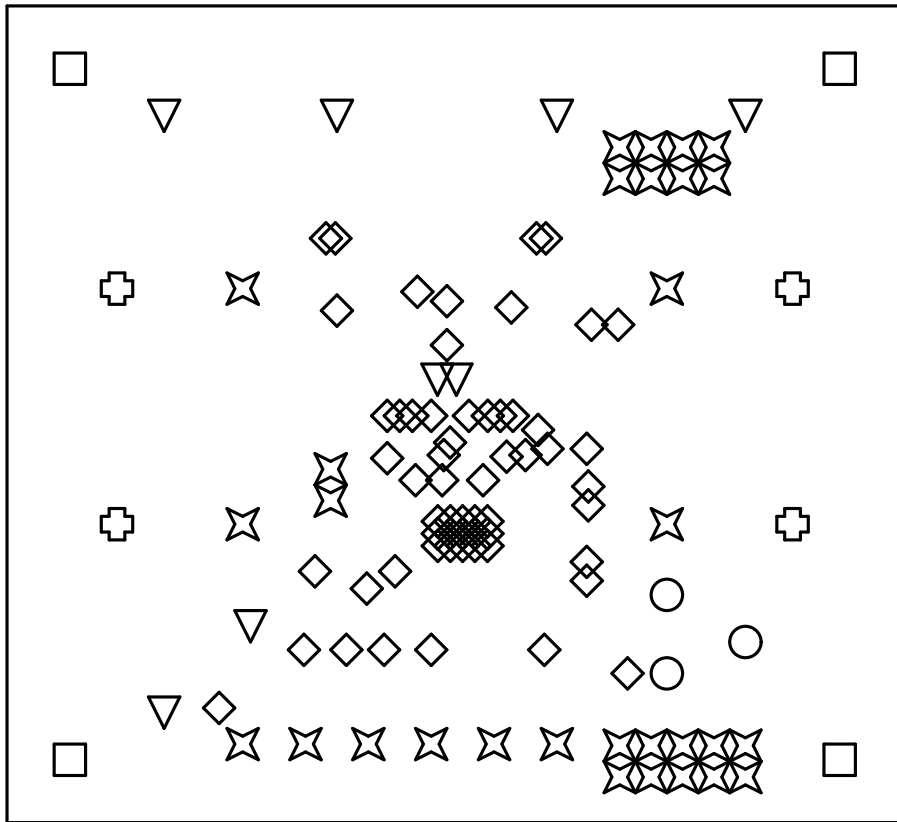
GENERATED : 4/7/2015 11:31:43 AM

TEXAS INSTRUMENTS



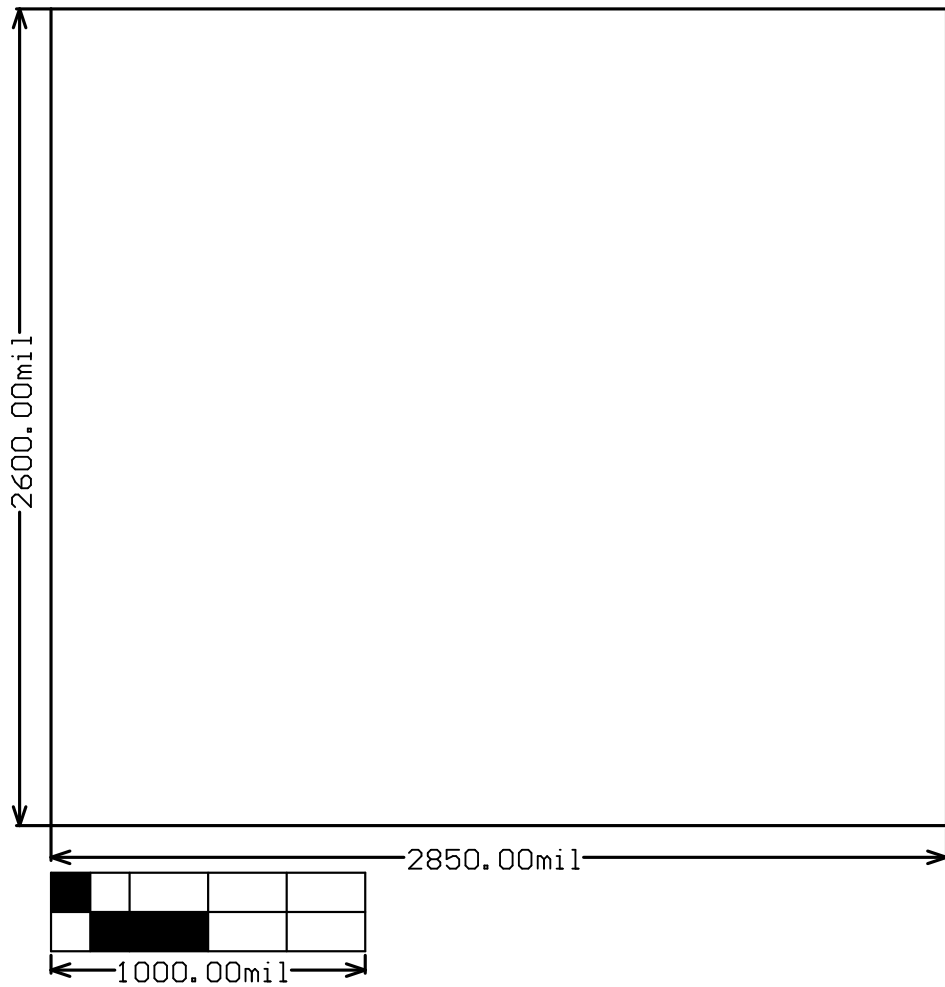
|                                  |                                  |                   |                                |
|----------------------------------|----------------------------------|-------------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP10624                | REV: A            | SUN REV: Not In VersionControl |
| LAYER NAME = Bottom Overlay      |                                  |                   |                                |
| PLOT NAME = Bottom Overlay       | GENERATED : 4/7/2015 11:31:44 AM | TEXAS INSTRUMENTS |                                |





| Symbol | Quantity  | Finished Hole Size  | Plated | Hole Type |
|--------|-----------|---------------------|--------|-----------|
| ◇      | 59        | 10.00mil (0.254mm)  | PTH    | Round     |
| ▽      | 8         | 20.00mil (0.508mm)  | PTH    | Round     |
| ✖      | 30        | 40.00mil (1.016mm)  | PTH    | Round     |
| ○      | 3         | 98.43mil (2.500mm)  | PTH    | Round     |
| □      | 4         | 125.98mil (3.200mm) | PTH    | Round     |
| ⊕      | 4         | 270.00mil (6.858mm) | PTH    | Round     |
|        | 108 Total |                     |        |           |

|                                  |                      |             |                                |
|----------------------------------|----------------------|-------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP10624    | REV: A      | SUN REV: Not In VersionControl |
| LAYER NAME = Drill Drawing       |                      |             |                                |
| PLOT NAME = Drill Drawing        | GENERATED : 4/7/2015 | 11:31:45 AM | TEXAS INSTRUMENTS              |



|                                  |                      |             |                                |
|----------------------------------|----------------------|-------------|--------------------------------|
| ALL ARTWORK VIEWED FROM TOP SIDE | BOARD #: PMP10624    | REV: A      | SUN REV: Not In VersionControl |
| LAYER NAME = M2 Board Dimensions |                      |             |                                |
| PLOT NAME = Board Dimensions     | GENERATED : 4/7/2015 | 11:31:46 AM | TEXAS INSTRUMENTS              |

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